

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	11076	atomic layer deposition or ald or ale or atomic layer epitaxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/23 09:32
L2	46	1 and back-to-back	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/23 09:34
L3	5049	1 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/23 09:34
L4	1	3 and dual substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/23 09:34
L8	279	dual substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/23 09:37
L9	5469	atomic layer deposition or ald	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/23 10:21
L10	2413	9 same (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/23 10:22
L11	268	10 same (two with (substrate or wafer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/23 10:47
L12	2	"20030209389".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/23 10:47
S1	4679	427/248.1,253,255.23,255.26,255.28,255.36.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 13:20

S2	183	S1 and (atomic layer deposition or ALD)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 13:21
S3	36	S2 and (coil\$3 or roll\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 13:54
S4	557	427/255.5.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 13:54
S5	5	S4 and (atomic layer deposition or ald)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 13:58
S6	5405	(atomic layer deposition or ald)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 13:58
S7	694	S6 and (coil\$3 or roll\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 14:02
S8	3	S6 and wire substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 13:58
S9	0	S6 and (coil\$3 or roll\$3) substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:44
S10	43	coiled substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 14:14
S11	153	S6 and web	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:07

S12	1	S2 and web	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 14:20
S13	110	S1 and web	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 14:21
S15	665	427/177,178,179.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:09
S16	101	S15 and coil\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:31
S18	137	S7 and batch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:31
S19	32	S7 and batch process	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:34
S21	818	427/209.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:35
S22	41	S21 and coil\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:41
S23	29	S21 and S15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:41
S24	10999	(atomic layer deposition or ald or ale or atomic layer epitaxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:45

S26	1105	S24 and (coil\$3 or spiral\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:46
S27	166	S26 and batch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:46
S28	57	S27 and batch process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:50
S29	361	S26 and (titanium or ti or titanium chloride or "ticl.sub.4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:51
S30	68	S29 and batch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:51
S31	6	S30 and web	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 15:51
S32	81	(peald or paald or ald or atomic layer deposition or ale or atomic layer epitaxy) and photovoltaic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 17:52
S33	7	S32 and tape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 17:53
S34	29823	(cvd or pvd or vapor deposition) and (coil or spring or shock)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 17:57
S35	11183	(cvd or pvd or vapor deposition) and spring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 17:56

S36	3712	(cvd or pvd or vapor deposition) and coil\$3 with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 18:00
S37	55	S36 and 427/248.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 18:00
S38	95	S35 and 427/248.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 18:06
S40	7	coating shock absorbers	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/17 18:06
S41	10999	atomic layer deposition or ald or ale or atomic layer epitaxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 10:26
S42	121	S41 same resistor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 09:10
S43	2	S42 same (TiO2 or ticl4 or titanium oxide or titanium chloride or "tio. sub.2" or "ticl.sub.4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 09:04
S44	10	S42 and (TiO2 or ticl4 or titanium oxide or titanium chloride or "tio. sub.2" or "ticl.sub.4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 09:21
S45	1201	S41 and resistor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 09:10
S46	236	S45 and (TiO2 or ticl4 or titanium oxide or titanium chloride or "tio. sub.2" or "ticl.sub.4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 09:33

S47	37525	spray coat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 10:15
S48	142	S47 same resistor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 09:21
S49	18	S48 and (TiO2 or ticl4 or titanium oxide or titanium chloride or "tio. sub.2" or "ticl.sub.4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 09:21
S50	19	S46 and (coil or spiral)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 09:32
S51	211	S41 and inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 09:32
S52	48	S51 and (TiO2 or ticl4 or titanium oxide or titanium chloride or "tio. sub.2" or "ticl.sub.4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 09:33
S53	276464	spray coat\$3 or cvd or pvd or vapor deposition	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 10:16
S54	1797	S53 and ((resistor or inductor) same (spiral or coil))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 10:17
S55	14	S54 and (Ticl4 or titanium tetrachloride or "ticl.sub.4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 10:18
S56	0	S41 same spiral inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 10:27

S57	7	S41 and spiral inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 10:47
S59	10999	atomic layer deposition or ald or ale or atomic layer epitaxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 12:25
S60	211	S59 and inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 12:25
S61	10	S59 same inductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 12:25
S62	0	ep1280629.pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 13:29
S63	0	ep1280629	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 13:29
S64	0	ep1280629a1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 13:29
S65	361	427/177.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 15:20
S66	120	(ald or atomic layer deposition) same (titanium tetrachloride or "TiCl.sub.4") same (titanium nitride or TiN)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 13:54
S67	4	S66 same water	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 15:50

S69	314	427/300.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 16:06
S70	5636	double sided tape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 16:06
S71	1602	S70 and coating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 16:06
S72	357	S71 and web	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 16:06
S73	294	S70 same coating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 16:07
S76	28	S73 same separat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 16:09
S77	29912	winding with film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 16:11
S78	12	S77 and (ald or ale or atomic layer (deposition or epitaxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 16:28
S85	16475	wrapping with film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 16:28
S86	13	S85 and (ald or ale or atomic layer (deposition or epitaxy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/18 16:29



S87	17	roll\$3 with source with carousel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:10
S88	27399	Wrap\$3 with (tape or web)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:14
S89	122779	roll\$3 with (tape or web)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:15
S90	25490	roll\$3 near (tape or web)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:13
S91	10108	roll near web	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:13
S92	5	S88 and ald	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:13
S93	5840	Wrap\$3 with (tape or web).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:36
S94	56274	roll\$3 with (tape or web).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:15
S95	1	S94 and ald	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:15
S96	192	back to back	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:37

S99	278	dual substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:38
S10 0	30	S99 and coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/23 09:47
S10 2	20522	back-to-back	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:51
S10 3	3655	S102 and (tape or web)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:51
S10 5	2213	S102 and web	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:52
S10 6	2	S105 and (atomic layer deposition or ald or atomic layer epitaxy or ale)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:53
S10 7	329	back-to-back with web	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 08:53
S10 8	122	(ald or atomic layer deposition) same (titanium tetrachloride or "Ticl.sub.4") same (titanium nitride or TiN)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 13:55
S10 9	4	S108 same water	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 13:54
S11 0	113	(ald or atomic layer deposition) same ( "Ticl.sub.4") same (titanium nitride or TiN)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 13:56

S11 1	33	S108 same barrier layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 14:11
S11 2	2	"6716693".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 14:14
S11 3	3597	copper interconnects	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 14:15
S11 4	58	S113 same (ald or atomic layer deposition or ale or atomic layer epitaxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 14:15
S11 5	1	S114 same water	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 15:39
S11 6	4	"3114539".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 15:40
S11 7	5	"3114539".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/05/19 15:40